## Electrical properties of MoS<sub>2</sub> TFTs with different layer thickness

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Molybdenum disulfide(MoS<sub>2</sub>) which is one of dichalcogenide materials, indicates semiconducting with a bandgap of  $1.2 \sim 1.8$  eV and it has unique electrical properties. These materials also apporopriate for flexible and transparent electronics and optical devices. Because of this reason, recently, MoS<sub>2</sub> was used for channel materials of TFTs.

In this paper, we fabricated the thin-film transistors with  $MoS_2$  as a channel material on a SiO<sub>2</sub>/Si substrate.  $MoS_2$  layers were exfoliated by mechanical exfoliation method, and transferred onto SiO<sub>2</sub>/Si substrate. After separating several different thickness of  $MoS_2$ , the thickness and numbers of layer of  $MoS_2$  were checked by Atomic Force Microscopy(AFM), Raman spectroscopy and Photoluminescence(PL) measurement.

Thin-film transistors with different number of  $MoS_2$  layer(1-layer, 3-layer, 6-layer, 10-layer) as a channel region were fabricated by photolithography using electron-beam evaporator(E-Beam evaporator), and we measured their electrical properties. In conclusion, the highest electron mobility was obtained at 6-layered  $MoS_2$  TFT, and threshold voltages were decreased as thickness of  $MoS_2$  is higher.



Fig. 1. Transfer characteristics of  $MoS_2$  TFTs at  $V_{ds} = 0.4$  V

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